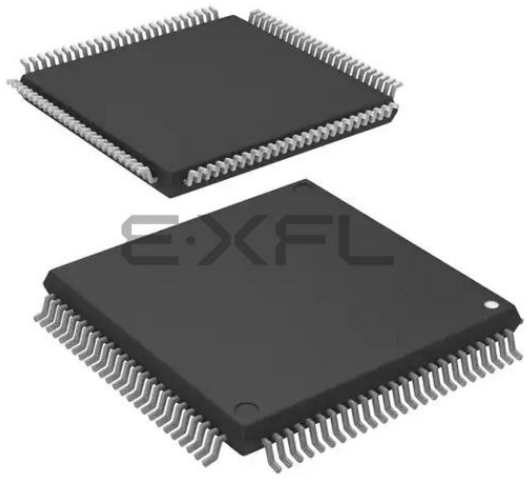

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SCI, SPI, SSI, USB OTG
Peripherals	DMA, LCD, LVD, POR, PWM, WDT
Number of I/O	80
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51135adfp-3a

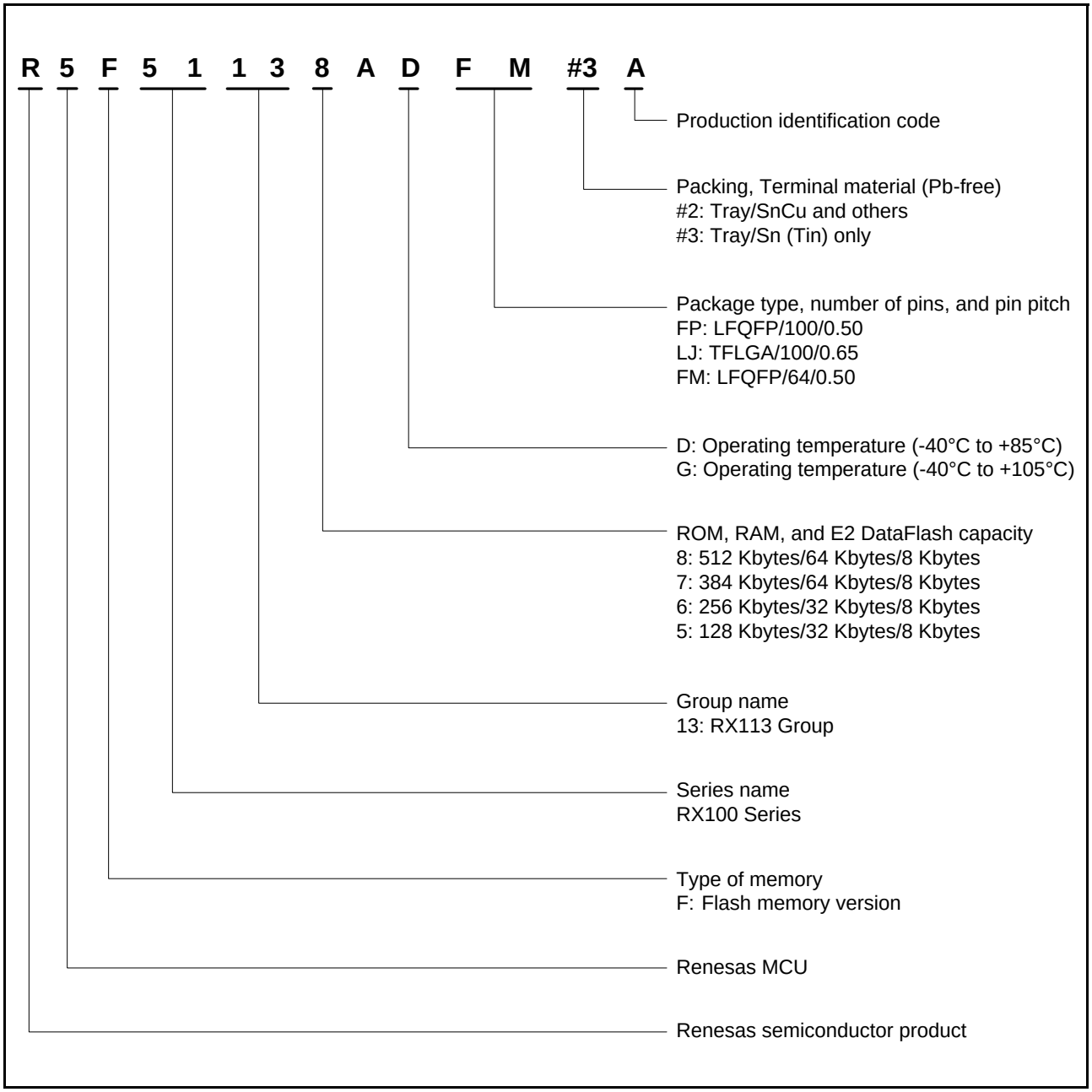


Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type

Table 1.7 List of Pins and Pin Functions (64-Pin LFQFP) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC, TMR)	Communication (SCIe, SCIf, RSPI, RIIC, USB, SSI)	LCD, Touch	Others
1		PJ0				DA0
2		P27	MTIOC2B/TMCI3	SCK1/SCK12/RXD6/SMISO6/ SSCL6		IRQ3/CMPA2/ CACREF/ ADTRG0#
3		P26	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1/ USB0_VBUSEN/TXD6/SMOSI6/ SSDA6		
4		P30	MTIOC4B/POE8#/TMRI3	RXD1/SMISO1/SSCL1	CAPH	IRQ0
5		P31	MTIOC4D/TMCI2	CTS1#/RTS1#/SS1#	CAPL	IRQ1
6	MD					FINED
7	RES#					
8	XCOUT					
9	XCIN	PH7				
10	UPSEL	P35				NMI
11	XTAL					
12	EXTAL					
13	VCL					
14	VSS					
15	VCC					
16		P32	MTIOC0C/RTCOUT/ TMO3	TXD6/SMOSI6/SSDA6/CTS6#/ RTS6#/SS6#		IRQ2
17		P17	MTIOC0C/MTIOC3A/ MTIOC3B/POE8#/TMO1	SCK1/MISOA/SDA0/RXD12/ RXDX12/SMISO12/SSCL12		IRQ7
18		P16	MTIOC3C/MTIOC3D/ RTCOUT/TMO2	TXD1/SMOSI1/SSDA1/MOSIA/ SCL0/USB0_VBUS/ USB0_VBUSEN/USB0_OVRCURB		IRQ6/ADTRG0#
19		P15	MTIOC0B/MTCLKB/ TMCI2	RXD1/SMISO1/SSCL1/RSPCKA		IRQ5/CLKOUT/ CACREF
20	UB#	P14	MTIOC0A/MTIOC3A/ MTCLKA/TMRI2	CTS1#/RTS1#/SS1#/SSLA0/ TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12/USB0_OVRCURA		IRQ4
21	VCC_USB					
22				USB0_DM		
23				USB0_DP		
24	VSS_USB					
25		P55	MTIOC4D/TMO3		VL1	
26		P54	MTIOC4B/TMCI1		VL2	
27		PC7	MTIOC3A/MTCLKB/ TMO2	TXD1/SMOSI1/SSDA1/MISOA/ TXD8/SMOSI8/SSDA8/ USB0_OVRCURB	VL3	CACREF
28		PC6	MTIOC3C/MTCLKA/ TMCI2	RXD1/SMISO1/SSCL1/MOSIA/ RXD8/SMISO8/SSCL8/ USB0_EXICEN	VL4	
29		PC5	MTIOC3B/MTCLKD/ TMRI2	SCK1/RSPCKA/SCK8/USB0_ID	COM0	
30		PC4	MTIOC3D/MTCLKC/ POE0#/TMCI1	SSLA0/CTS8#/RTS8#/SS8#/SCK5/ USB0_VBUSEN/USB0_VBUS *1	COM1	IRQ2/CLKOUT
31		PC3	MTIOC4D	TXD5/SMOSI5/SSDA5/IRTXD5	COM2	
32		PC2	MTIOC4B	RXD5/SMISO5/SSCL5/SSLA3/ IRRXD5	COM3	

Table 4.1 List of I/O Registers (Address Order) (11/23)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 8722h	MTU0	Timer General Register F	TGRF	16	16	2 or 3 PCLKB
0008 8724h	MTU0	Timer Interrupt Enable Register 2	TIER2	8	8	2 or 3 PCLKB
0008 8726h	MTU0	Timer Buffer Operation Transfer Mode Register	TBTM	8	8	2 or 3 PCLKB
0008 8780h	MTU1	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8781h	MTU1	Timer Mode Register	TMDR	8	8	2 or 3 PCLKB
0008 8782h	MTU1	Timer I/O Control Register	TIOR	8	8	2 or 3 PCLKB
0008 8784h	MTU1	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 8785h	MTU1	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8786h	MTU1	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8788h	MTU1	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 878Ah	MTU1	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 8790h	MTU1	Timer Input Capture Control Register	TICCR	8	8	2 or 3 PCLKB
0008 8800h	MTU2	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8801h	MTU2	Timer Mode Register	TMDR	8	8	2 or 3 PCLKB
0008 8802h	MTU2	Timer I/O Control Register	TIOR	8	8	2 or 3 PCLKB
0008 8804h	MTU2	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 8805h	MTU2	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8806h	MTU2	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8808h	MTU2	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 880Ah	MTU2	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 8880h	MTU5	Timer Counter U	TCNTU	16	16	2 or 3 PCLKB
0008 8882h	MTU5	Timer General Register U	TGRU	16	16	2 or 3 PCLKB
0008 8884h	MTU5	Timer Control Register U	TCRU	8	8	2 or 3 PCLKB
0008 8886h	MTU5	Timer I/O Control Register U	TIORU	8	8	2 or 3 PCLKB
0008 8890h	MTU5	Timer Counter V	TCNTV	16	16	2 or 3 PCLKB
0008 8892h	MTU5	Timer General Register V	TGRV	16	16	2 or 3 PCLKB
0008 8894h	MTU5	Timer Control Register V	TCRV	8	8	2 or 3 PCLKB
0008 8896h	MTU5	Timer I/O Control Register V	TIORV	8	8	2 or 3 PCLKB
0008 88A0h	MTU5	Timer Counter W	TCNTW	16	16	2 or 3 PCLKB
0008 88A2h	MTU5	Timer General Register W	TGRW	16	16	2 or 3 PCLKB
0008 88A4h	MTU5	Timer Control Register W	TCRW	8	8	2 or 3 PCLKB
0008 88A6h	MTU5	Timer I/O Control Register W	TIORW	8	8	2 or 3 PCLKB
0008 88B2h	MTU5	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 88B4h	MTU5	Timer Start Register	TSTR	8	8	2 or 3 PCLKB
0008 88B6h	MTU5	Timer Compare Match Clear Register	TCNTCMPCLR	8	8	2 or 3 PCLKB
0008 8900h	POE	Input Level Control/Status Register 1	ICSR1	16	8, 16	2 or 3 PCLKB
0008 8902h	POE	Output Level Control/Status Register 1	OCSR1	16	8, 16	2 or 3 PCLKB
0008 8908h	POE	Input Level Control/Status Register 2	ICSR2	16	8, 16	2 or 3 PCLKB
0008 890Ah	POE	Software Port Output Enable Register	SPOER	8	8	2 or 3 PCLKB
0008 890Bh	POE	Port Output Enable Control Register 1	POECR1	8	8	2 or 3 PCLKB
0008 890Ch	POE	Port Output Enable Control Register 2	POECR2	8	8	2 or 3 PCLKB
0008 890Eh	POE	Input Level Control/Status Register 3	ICSR3	16	8, 16	2 or 3 PCLKB
0008 9000h	S12AD	A/D Control Register	ADCSR	16	16	2 or 3 PCLKB
0008 9004h	S12AD	A/D Channel Select Register A	ADANSA	16	16	2 or 3 PCLKB
0008 9006h	S12AD	A/D Channel Select Register A1	ADANSA1	16	16	2 or 3 PCLKB
0008 9008h	S12AD	A/D-Converted Value Addition Mode Select Register	ADADS	16	16	2 or 3 PCLKB
0008 900Ah	S12AD	A/D-Converted Value Addition Mode Select Register 1	ADADS1	16	16	2 or 3 PCLKB
0008 900Ch	S12AD	A/D-Converted Value Addition Count Select Register	ADADC	8	8	2 or 3 PCLKB
0008 900Eh	S12AD	A/D Control Extended Register	ADCER	16	16	2 or 3 PCLKB
0008 9010h	S12AD	A/D Start Trigger Select Register	ADSTRGR	16	16	2 or 3 PCLKB
0008 9012h	S12AD	A/D Converted Extended Input Control Register	ADEXICR	16	16	2 or 3 PCLKB
0008 9014h	S12AD	A/D Channel Select Register B	ADANSB	16	16	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (16/23)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 B331h	SCI12	Timer Mode Register	TMR	8	8	2 or 3 PCLKB
0008 B332h	SCI12	Timer Prescaler Register	TPRE	8	8	2 or 3 PCLKB
0008 B333h	SCI12	Timer Count Register	TCNT	8	8	2 or 3 PCLKB
0008 C000h	PORT0	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C001h	PORT1	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C002h	PORT2	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C003h	PORT3	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C004h	PORT4	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C005h	PORT5	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C009h	PORT9	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ah	PORTA	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Bh	PORTB	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ch	PORTC	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Dh	PORTD	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Eh	PORTE	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Fh	PORTF	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C012h	PORTJ	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C020h	PORT0	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C021h	PORT1	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C022h	PORT2	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C023h	PORT3	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C024h	PORT4	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C025h	PORT5	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C029h	PORT9	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Ah	PORTA	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Bh	PORTB	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Ch	PORTC	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Dh	PORTD	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Eh	PORTE	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C02Fh	PORTF	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C032h	PORTJ	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C040h	PORT0	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C041h	PORT1	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C042h	PORT2	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C043h	PORT3	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C044h	PORT4	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C045h	PORT5	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C049h	PORT9	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing
0008 C04Ah	PORTA	Port Input Data Register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)	V_{IH}	VCC × 0.7	—	5.8	V	
	Ports P16, P17, port PA6, port PB0 (5 V tolerant)		VCC × 0.8	—	5.8		
	Ports P02, P04, P07, ports P10 to P15, ports P20 to P27, ports P30 to P32, P35, ports P50 to P56, ports PA0 to PA5, PA7, ports PB1 to PB7, ports PC0 to PC7, ports PD0 to PD4, ports PE0 to PE7, ports PF6, PF7, port PH7, ports PJ0*1, PJ2*1, PJ3, RES#		VCC × 0.8	—	VCC + 0.3		
	RIIC input pin (except for SMBus)	V_{IL}	–0.3	—	VCC × 0.3		
	Other than RIIC input pin		–0.3	—	VCC × 0.2		
	RIIC input pin (except for SMBus)	ΔV_T	VCC × 0.05	—	—		
	Other than RIIC input pin		VCC × 0.1	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	RIIC input pin (SMBus)		2.1	—	VCC + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		
	RIIC input pin (SMBus)		–0.3	—	0.8		

Note 1. There are restrictions on AVCC0 and VCC depending on the usage conditions for the 12-bit D/A converter and I/O ports. When using ports PJ0 and PJ2 multiplexed with DA0 and DA1 as general I/O ports, make sure that VCC ≤ AVCC0.

Table 5.4 DC Characteristics (2)

Conditions: 1.8 V ≤ VCC = VCC_USB < 2.7 V, 1.8 V ≤ AVCC0 < 2.7 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	Ports P16, P17, port PA6, port PB0 (5 V tolerant)	V_{IH}	VCC × 0.8	—	5.8	V	
	Ports P02, P04, P07, ports P10 to P15, ports P20 to P27, ports P30 to P32, P35, ports P50 to P56, ports PA0 to PA5, PA7 ports PB1 to PB7, ports PC0 to PC7, ports PD0 to PD4, ports PE0 to PE7, ports PF6, PF7, port PH7, ports PJ0*1, PJ2*1, PJ3, RES#		VCC × 0.8	—	VCC + 0.3		
	All pins	V_{IL}	–0.3	—	VCC × 0.2		
	All pins	ΔV_T	VCC × 0.01	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		

Note 1. There are restrictions on AVCC0 and VCC depending on the usage conditions for the 12-bit D/A converter and I/O ports. When using ports PJ0 and PJ2 multiplexed with DA0 and DA1 as general I/O ports, make sure that VCC ≤ AVCC0.

Table 5.5 DC Characteristics (3)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input leakage current	RES#, MD, port P35, port PH7	$\lvert I_{in} \rvert$	—	—	1.0	µA	V_{in} = 0 V, VCC
Three-state leakage current (off-state)	Ports for 5 V tolerant	$\lvert I_{TSI} \rvert$	—	—	1.0	µA	V_{in} = 0 V, 5.8 V
	Pins other than above		—	—	1.0		V_{in} = 0 V, VCC
Input capacitance	All input pins (except for port P16, port P35, USB0_DM, USB0_DP)	C_{in}	—	—	15	pF	V_{in} = 0 V Frequency: 1 MHz T_a = 25°C
	Port P16, port P35, USB0_DM, USB0_DP		—	—	30		

Table 5.6 DC Characteristics (4)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input pull-up resistor	All ports (except for ports P35, PH7)	R_U	10	20	100	kΩ	V_{in} = 0 V

Table 5.14 DC Characteristics (12)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Permissible error of VCL pin external capacitance	C_{VCL}	1.4	4.7	7.0	μF	

Note: The recommended capacitance is 4.7 μF. Variations in connected capacitors should be within the above range.

Table 5.15 Permissible Output Currents (1)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V,
T_a = –40 to +85°C (D version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7	ΣI_{OL}	2.4	
	Total of ports P02, P04, P07, P20 to P27, P30, P31, PJ0, PJ2, PJ3		30	
	Total of ports P10 to P17, port P32, ports P50 to P56, ports PB0 to PB7, ports PC0 to PC7		30	
	Total of ports PA0 to PA7, ports PD0 to PD4, ports PE0 to PE7, ports PF6, PF7		30	
	Total of all output pins		60	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P02, P04, P07, P20 to P27, P30, P31, PJ0, PJ2, PJ3		–10	
	Total of ports P10 to P17, port P32, ports P50 to P56, ports PB0 to PB7, ports PC0 to PC7		–15	
	Total of ports PA0 to PA7, ports PD0 to PD4, ports PE0 to PE7, ports PF6, PF7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

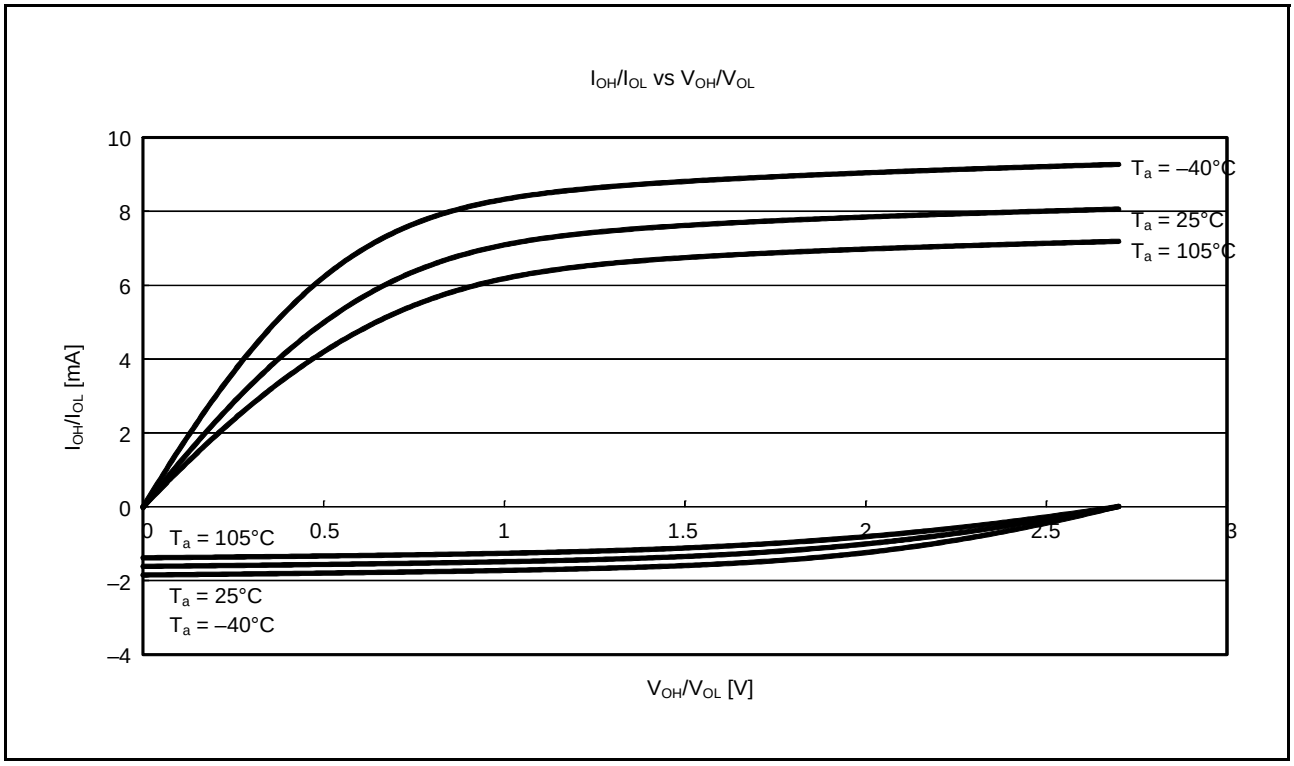


Figure 5.16 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports P90 to P92, Ports PJ6, PJ7 at VCC = 2.7 V (Reference Data)

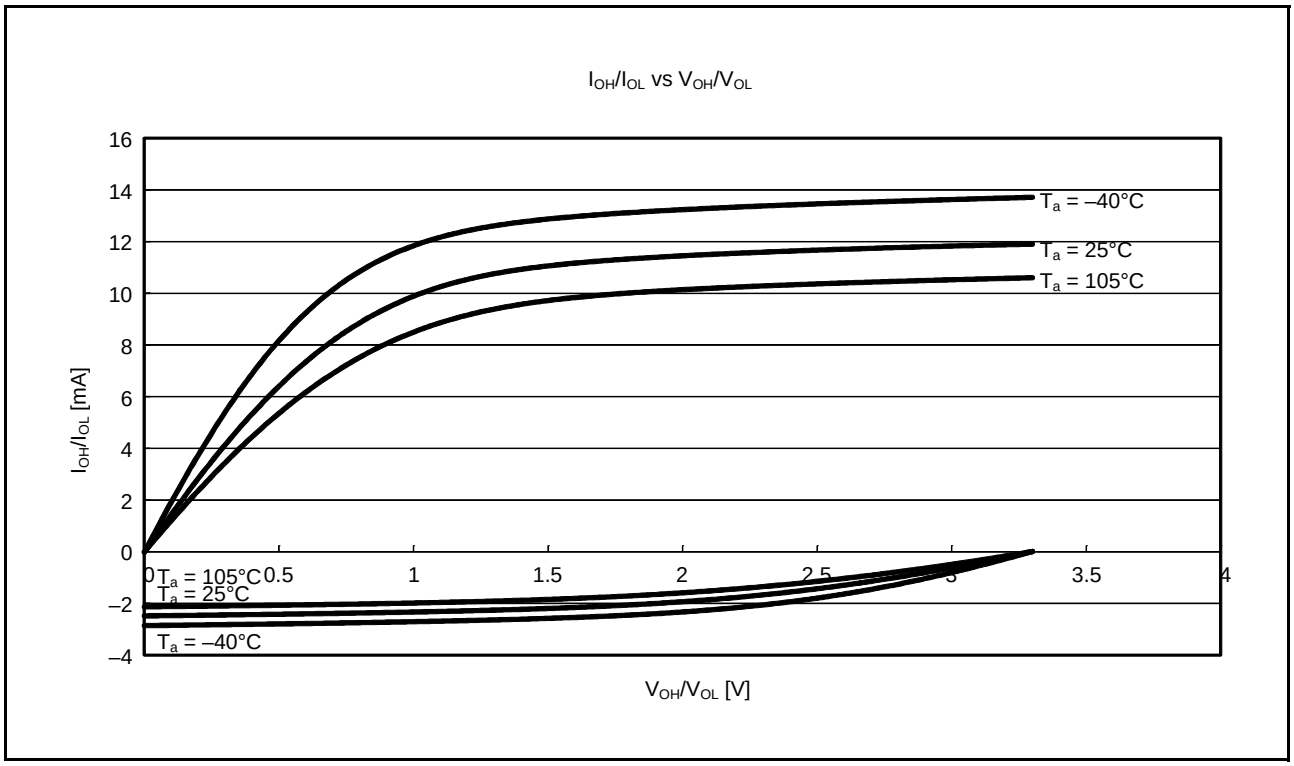


Figure 5.17 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of Ports P40 to P44, P46, Ports P90 to P92, Ports PJ6, PJ7 at VCC = 3.3 V (Reference Data)

5.3 AC Characteristics

5.3.1 Clock Timing

Table 5.19 Operation Frequency Value (High-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC				Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	When USB in Use*4	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	16	32	32	MHz
	FlashIF clock (FCLK)*1, *2		8	16	32	32	
	Peripheral module clock (PCLKB)		8	16	32	32	
	Peripheral module clock (PCLKD)*3		8	16	32	32	
	USB clock (UCLK)	f_{usb}	—	—	—	48	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.
Note 4. The VCC_USB range is 3.0 to 3.6 V when the USB clock is in use.

Table 5.20 Operation Frequency Value (Middle-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC				Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	When USB in Use*4	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	12	12	12	MHz
	FlashIF clock (FCLK)*1, *2		8	12	12	12	
	Peripheral module clock (PCLKB)		8	12	12	12	
	Peripheral module clock (PCLKD)*3		8	12	12	12	
	USB clock (UCLK)	f_{usb}	—	—	—	48	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.
Note 4. The VCC_USB range is 3.0 to 3.6 V when the USB clock is in use.

Table 5.21 Operation Frequency Value (Low-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	32.768			kHz
	FlashIF clock (FCLK)*1		32.768			
	Peripheral module clock (PCLKB)		32.768			
	Peripheral module clock (PCLKD)*2		32.768			

Note 1. Programming and erasing the flash memory is impossible.
Note 2. The A/D converter cannot be used.

Table 5.33 Timing of On-Chip Peripheral Modules (4)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz,
T_a = –40 to +105°C

Item		Symbol	Min.*1	Max.	Unit	Test Conditions
RIIC (Standard mode, SMBus)	SCL0 input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	—	ns	Figure 5.49
	SCL0 input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0 input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0, SDA0 input rise time	t_{Sr}	—	1000	ns	
	SCL0, SDA0 input fall time	t_{Sf}	—	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA0 input bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition input hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition input setup time	t_{STAS}	1000	—	ns	
	STOP condition input setup time	t_{STOS}	1000	—	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	
RIIC (Fast mode)	SCL0 input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 600	—	ns	Figure 5.49
	SCL0 input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0 input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0, SDA0 input rise time	t_{Sr}	—*2	300	ns	
	SCL0, SDA0 input fall time	t_{Sf}	—*2	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA0 input bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition input hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition input setup time	t_{STAS}	300	—	ns	
	STOP condition input setup time	t_{STOS}	300	—	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	

Note: t_{IICcyc}: RIIC internal reference count clock (IICφ) cycle
Note 1. The value in parentheses is used when the ICMR3.NF[1:0] bits are set to 11b while a digital filter is enabled with the ICFER.NFE bit = 1.
Note 2. The minimum tsr and tsf specifications for fast mode are not set.

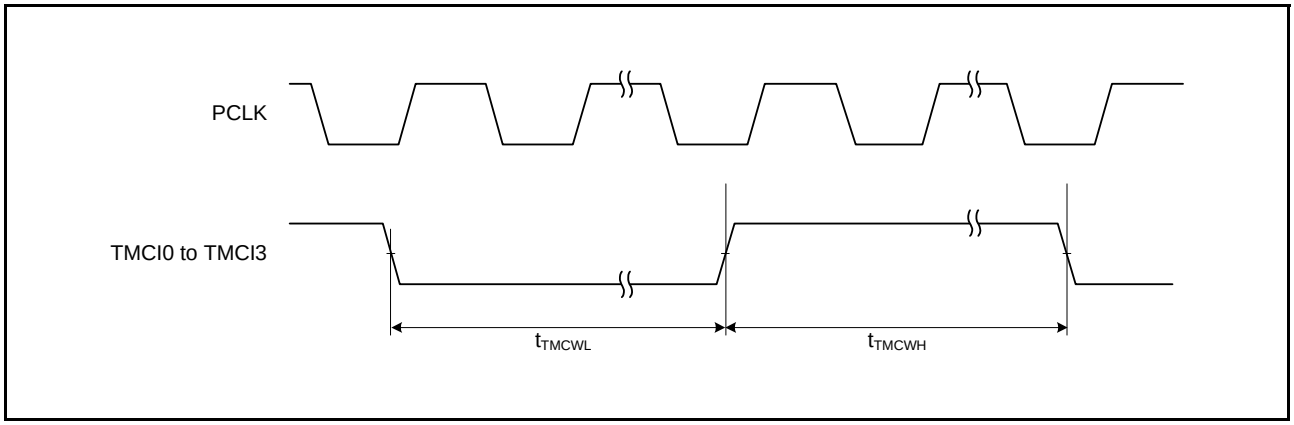


Figure 5.37 TMR Clock Input Timing

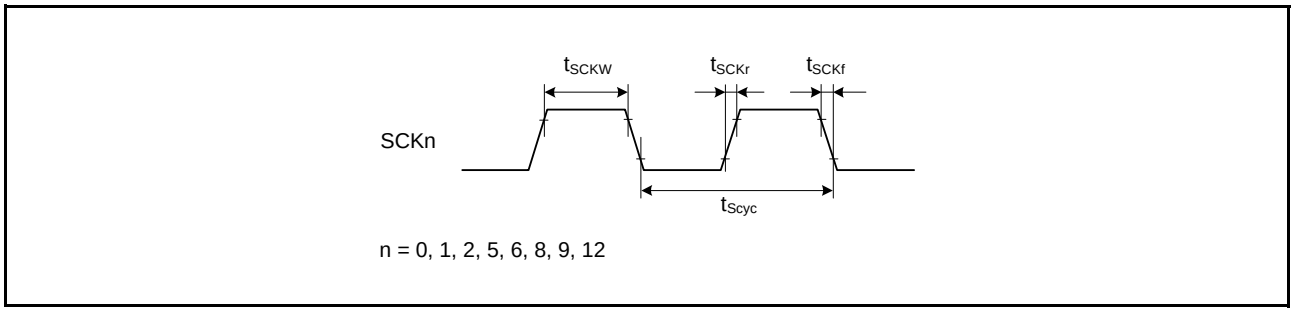


Figure 5.38 SCK Clock Input Timing

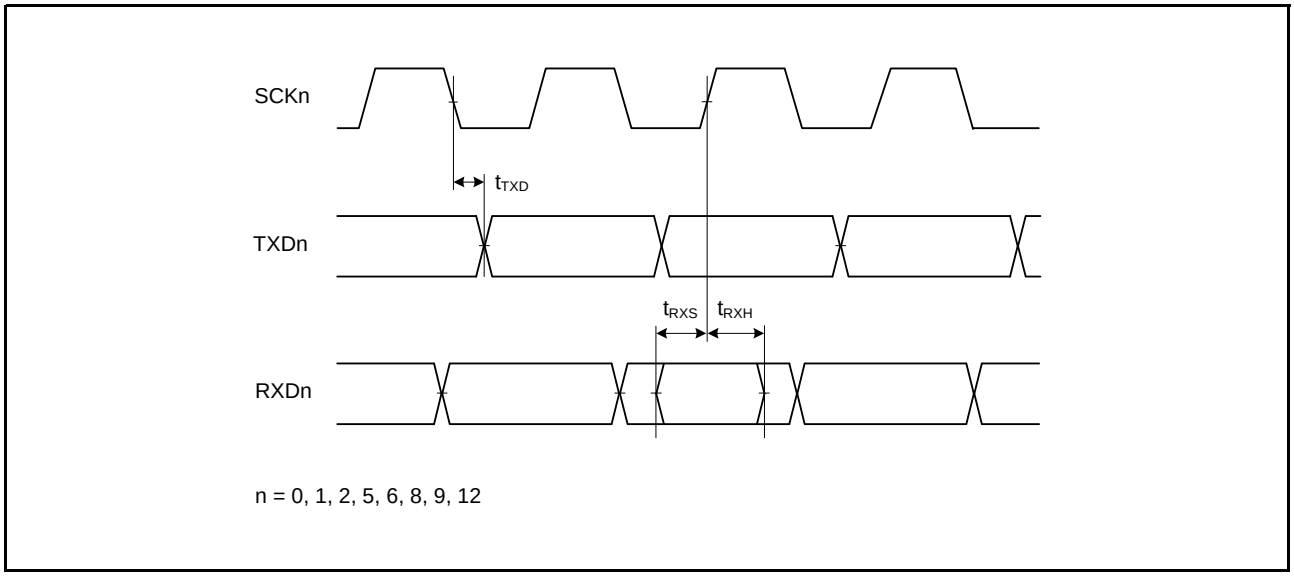


Figure 5.39 SCI Input/Output Timing: Clock Synchronous Mode

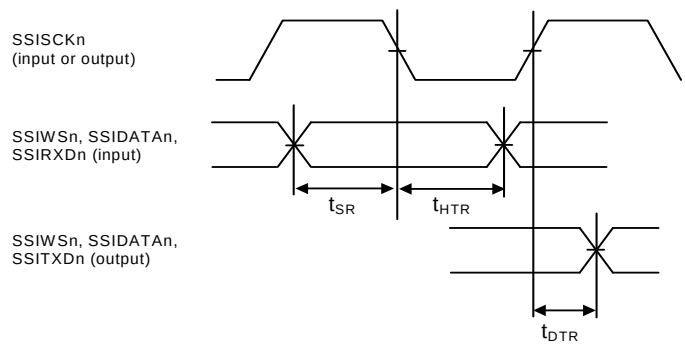
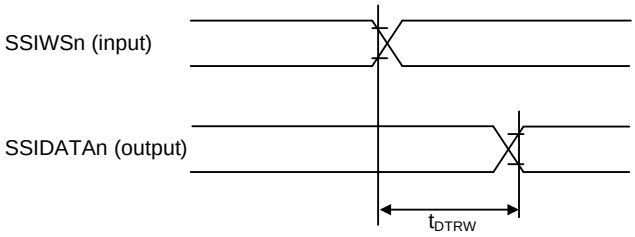


Figure 5.52 Transmission/Reception Timing (Synchronized with SSISCKn Falling Edge)



Note. Timing to output the MSB bit during slave transmission from SSIWSn
when DEL = 1 and SDTA = 0 or DEL = 1, SDTA = 1, and SWL[2:0] = DWL[2:0]

Figure 5.53 SSIDATA Output Delay After SSIWSn Changing Edge

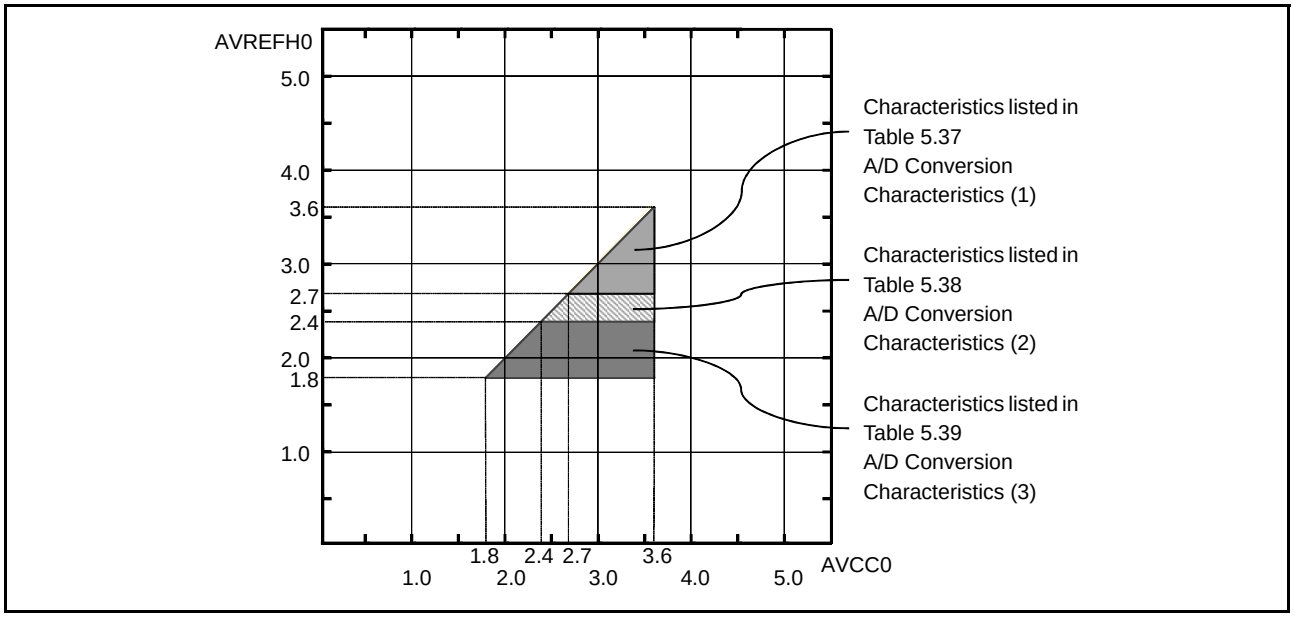


Figure 5.56 AVCC0 to AVREFH0 Voltage Range

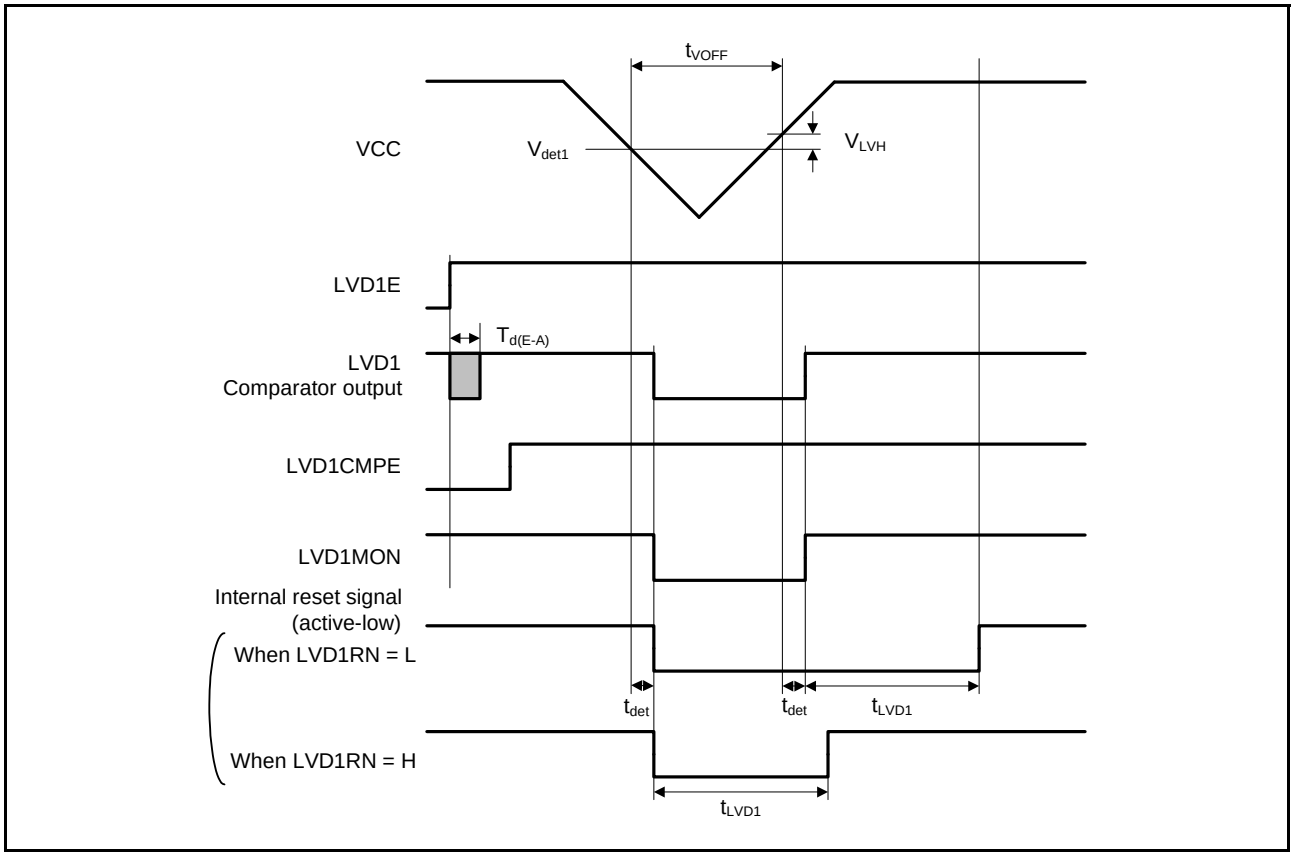


Figure 5.64 Voltage Detection Circuit Timing (V_{det1})

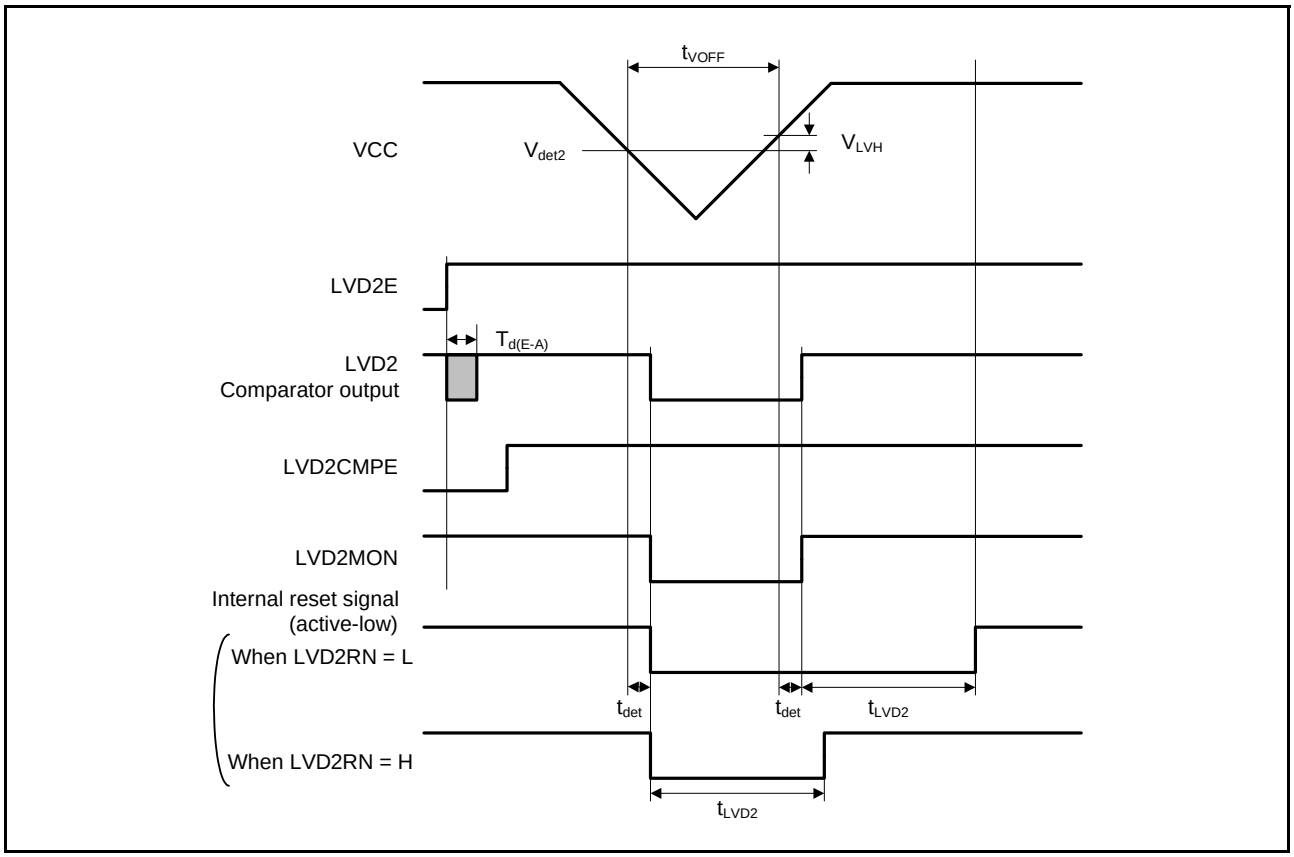


Figure 5.65 Voltage Detection Circuit Timing (V_{det2})

Table 5.62 ROM (Flash Memory for Code Storage) Characteristics (3)

Middle-speed operating mode Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +85°C

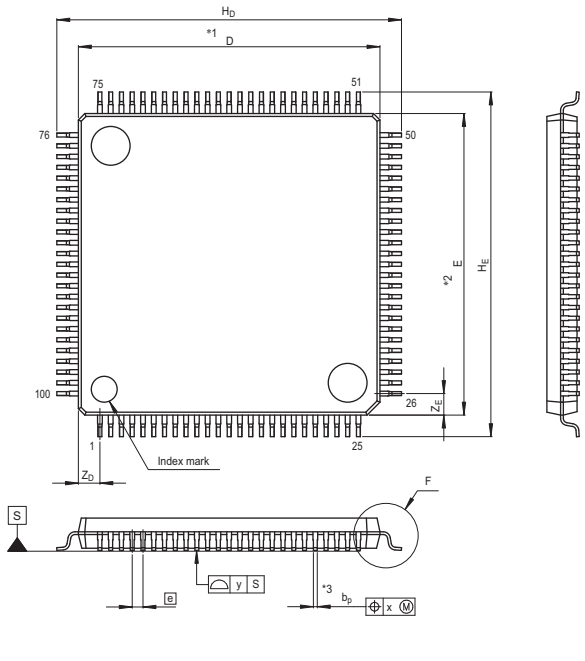
Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	4-byte	t_{P4}	—	143	1330	—	96.8	932	µs
Erasure time	1-Kbyte	t_{E1K}	—	8.3	269	—	5.85	219	ms
	256-Kbyte	t_{E256K}	—	407	928	—	93	520	ms
Blank check time	4-byte	t_{BC4}	—	—	78	—	—	50	µs
	1-Kbyte	t_{BC1K}	—	—	1.61	—	—	0.369	ms
Erase operation forcible stop time		t_{SED}	—	—	33.6	—	—	25.6	µs
Start-up area switching setting time		t_{SAS}	—	13.2	549	—	7.6	445	ms
Access window time		t_{AWS}	—	13.2	549	—	7.6	445	ms
ROM mode transition wait time 1		t_{DIS}	2	—	—	2	—	—	µs
ROM mode transition wait time 2		t_{MS}	3	—	—	3	—	—	µs

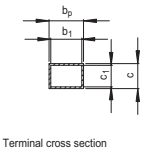
Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

Appendix 1. Package Dimensions

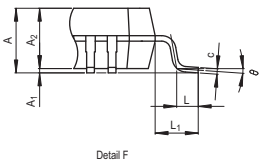
Information on the latest version of the package dimensions or mountings has been displayed in “Packages” on Renesas Electronics Corporation website.

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g





Terminal cross section



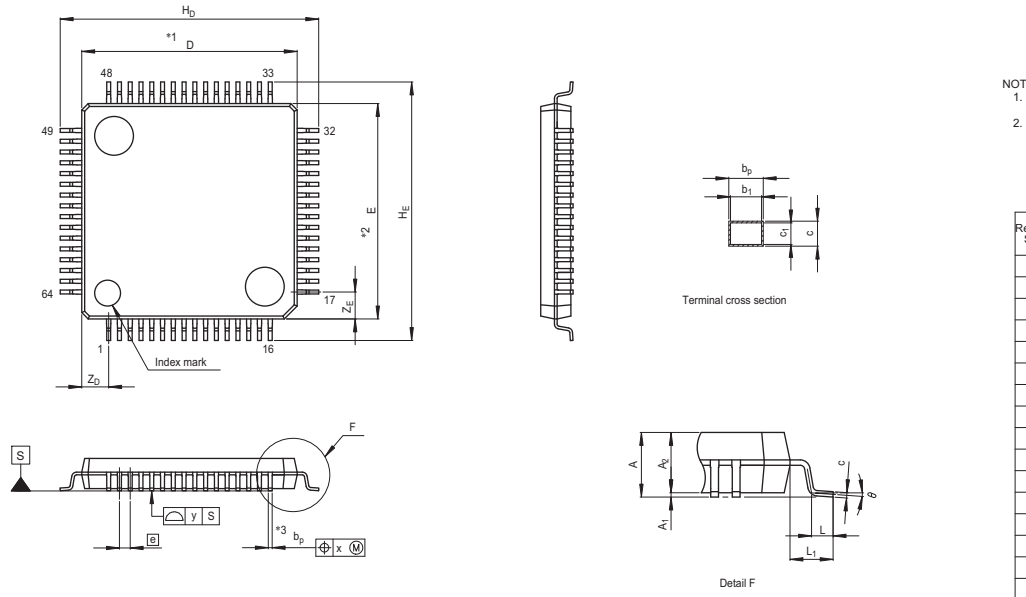
Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure A 100-Pin LFQFP (PLQP0100KB-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure C 64-Pin LFQFP (PLQP0064KB-A)

REVISION HISTORY	RX113 Group Datasheet

Classifications

- Items with Technical Update document number: Changes according to the corresponding issued Technical Update
- Items without Technical Update document number: Minor changes that do not require Technical Update to be issued

Rev.	Date	Description		Classification
		Page	Summary	
1.02	Dec 01, 2014	—	First edition, issued	
1.10	Mar 31, 2016	1. Overview		
		16 to 23	Table 1.5 to 1.7 Note 2 regarding I/O power source is AVCC0 for the ports (P4, P9, PJ6, and P7), added	
		5. Electrical Characteristics		
		53	Table 5.1 Absolute Maximum Ratings, Analog power supply voltage added	TN-RX*-A149A/E
		54	Table 5.2 Recommended Operating Conditions, VREFH0 / VREFH / AVCC0 / VREFL added	TN-RX*-A149A/E
		60	Table 5.8 DC Characteristics (6), Increment for LPT operation and Increment for IWDT operation added	TN-RX*-A149A/E
		62	Table 5.9 DC Characteristics (7) added	TN-RX*-A136A/E
		62, 63	Table 5.10 DC Characteristics (8), LDV1,2 and CTSU operating current added	TN-RX*-A149A/E
		65, 66	Table 5.15 Permissible Output Currents is divided into D version and G version	TN-RX*-A136A/E
		105	Table 5.43 D/A Conversion Characteristics (1), Output voltage range added	
		119	Table 5.61 ROM (Flash Memory for Code Storage) Characteristics (2), Erasure time - 256-Kbyte added	TN-RX*-A132A/E
		120	Table 5.62 ROM (Flash Memory for Code Storage) Characteristics (3), Temperature range for the programming/erasure operation changed and Erasure time - 256-Kbyte added	TN-RX*-A132A/E
		121	Table 5.64 E2 DataFlash Characteristics (2), Low speed FCLK changed and Erasure time - 8-Kbyte added	TN-RX*-A132A/E
		121	Table 5.65 E2 DataFlash Characteristics (3), Temperature range for the programming/erasure operation changed, Low speed FCLK changed and Erasure time - 8-Kbyte added	TN-RX*-A132A/E
		122 to 124	5.15 Usage Notes added	

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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